

# **Electrostatic Discharge**

## **Understand, Simulate, and Fix ESD Problems**

Third Edition

**Michel Mardiguian**



A John Wiley & Sons, Inc., Publication



# **Electrostatic Discharge**

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# Preface to the First Edition

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Static electricity is the most ancient form of electricity known to humans. More than 2000 years ago, the Greeks recognized the attraction between certain materials when they were rubbed together; indeed, the word *electricity* comes from the Greek *elektron*, which means amber. During the seventeenth and eighteenth centuries, several key experiments were conducted to understand and measure static electricity. But the discovery of electromagnetism and its formidable breakthrough has rapidly outgrown interest in static electricity. Even today, where the industrial applications of static electricity are not insignificant, they cannot compare with those of electromagnetism and electrodynamics.

Ironically, as much as static electricity was relegated to the attic of scientific evolution, she continuously occupied (I say “she” because electricity, in French, is feminine—don’t ask me why) the headlines with her undesirable effects. If we consider the thousands of lightning strikes hitting the terrestrial atmosphere every minute, we have to realize that our planet with its surrounding clouds is nothing more than a huge electrostatic machine constantly charging and discharging on itself. For decades, people have been learning the hard way that statics can cause explosions of fuels and ammunitions. In 1937, the German flying boat *Hindenburg* arriving in Lakehurst, New Jersey, caught fire while anchoring at its landing mast. What could have been a severe incident became a tragedy: Due to international tension, the United States had put an embargo on helium sales to Germany and the vessel was inflated with hydrogen instead. The resulting fire caused the death of 37 of its hundred or so passengers. Although the causes have not been completely understood, electrostatic discharge (ESD) is at the top of the list.

More recently, during the 1970s in the United States, a spacecraft launching rocket exploded during the fueling operation, killing three engineers. The cause was, beyond any doubt, identified as ESD. Satellites have paid a heavy toll because of ESD, from minor anomalies to severe malfunctions, as in the European Space Agency (ESA) MARECS satellite. In January 1985, during the assembly of a Pershing missile near Heilbronn, Germany, the motor case, made of Kevlar, was repeatedly rubbed against the cushioning in its container. The ensuing ESD caused the 4 tons of highly flammable propellant to catch fire and the motor exploded, blowing parts 125 meters away, killing three people and injuring nine.

Although such catastrophes are terrible and spectacular, they are quite rare; but a more insidious aspect of ESD bloomed in the early 1970s, with the massive

arrival of integrated microelectronics. The plants producing integrated circuits (ICs) started to experience disappointing percentage yields. Once thoroughly investigated, the problem was found to be largely due to ESD during all fabrication steps and handling. Although the problem has been fully explained and drastic solutions adopted, ESD is still costing millions of dollars a year of pure losses. Considering the astronomical quantities of ICs manufactured each year, the mere fact that 3 to 30% of them die in infancy because of ESD represents an impressive amount of money. To quote G. C. Quinn, technical editor of *Electronics Test Magazine* (April 1984): “The volume range of ESD sensitive components is rising faster than the development and usage of ESD protections . . . Estimating costs of ESD failures not caught at manufacturing inspection is far more difficult. Many of the degraded, walking-wounded devices may not show up until after termination of the manufacturer’s guarantee.” Around 1980, Lockheed Corporation reported a one-year cost savings of \$1.8 million through static protection measures, which reduced ESD-related failures by a 16 to 1 ratio. Arithmethic, then, tells us that Lockheed had endured losses of \$1.92 million the previous year. Even with severe protection measures, some manufacturers still confess that ESD is causing 39 to 48% of their IC rejects. The only hope that the plague will ever be dominated is a progressive awareness of people and the growing use of robots on manufacturing lines.

But the worst was yet to come: With the proliferation of microelectronics in all possible applications, an even bigger number of complaints flourished about ESD-related erratic bugs, transient malfunctions, erased memories, and the like. Although the economic losses resulting from erroneous transactions and corrupted data of all kinds are difficult to evaluate, it is probably an even larger figure than the one for chip damage during fabrication. It seems ironic that a physical fact, known for 2500 years as doing nothing but nasty things to us, has continued to defy electronics engineers. Solving the problem of transient errors induced by ESD has not been given the same concerted effort as the manufacturing aspect. Most early research was performed by isolated pioneers fighting with their own weapons. Initiating the research themselves, seldom supported by vast budgets, these men used their sagacity and all the resources they could find to investigate a problem for which no measuring techniques existed. They had to invent the tools they needed, and they had to be statisticians, chemists, and radio-frequency (RF) designers all at once. The names of Ted Madzy, W. Byrne, Michael King, Ralph Calcavecchio, Richard Simoncic, and many others that I don’t know of are the people to whom all of us who followed are indebted. By mentioning their work, this book will try to render a piece of the recognition they deserve: They paved the road for bringing the understanding of ESD from black magic up to an analytic method. We hope this book will demystify ESD and give a step-by-step strategy for predicting, testing, and reducing its effects on electronic equipment.

# Preface to the Third Edition

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The two previous editions of this book had a very favorable reception from the EMC community. However, the first and second editions, published by the EMC consulting firm Interference Control Technologies, had a rather limited distribution and have been out of print since the year 2000. A new edition was sorely needed, incorporating current technological advances with the needs of the engineering community.

Since the first edition of this book 22 years ago, the electrostatic discharge (ESD) phenomenon has continued to plague the electronic industry. In spite of undisputable progress in ESD awareness and protection measures, which are enforced by regular audits and accreditations, the “sleeping sentinel” syndrome takes its toll. Inspections often reveal that in an assumed static-free manufacturing chain, all but one of the workstations or handling/packing posts are adequately protected. This single defective link is enough to compromise the entire ESD line of defense. Sometimes it was the very apparatus intended to eliminate human influence, for example, automatic handling by robots, that created a new ESD problem, sometimes worse than the one it was supposed to cure.

Once these pernicious problems are fixed, the return on investment of a flawless ESD control program is often spectacular, not forgetting that this is a constant battle because today’s problem is frequently the consequence of some unanticipated effect of yesterday’s solution.

Nonetheless, once marketed and sold, some modern equipment, although it has undergone a complete EMC test program that includes ESD, is still experiencing malfunctions, a tangible share of which is traceable to ESD. Consider a recent example: This author, among other consultants, was asked to solve a problem on a certain model of car. Five percent of owners were experiencing a very unpleasant dashboard failure: During operation some displays would freeze up, eventually becoming totally dark without a possibility of reset, even after a stop-and-start action. The problem was a peculiar ESD configuration that had escaped the standard test program.

In order to cope with such omnipresent threats, intensive research has continued worldwide, using instrumentation that is much more elaborate than that available in the 1970s and 1980s to the pioneers of ESD studies. Recent studies have covered arc formation, initial spike with the hand/metal scenario, fields radiated in the vicinity of the discharge, and the like. Among the engineers who

investigated these facets of ESD, one of the most prolific has certainly been D. Pommerenke of Missouri University. In the first few chapters of this new edition, we give an overview of these recent studies.

The problem of poor repeatability has always also plagued ESD testing, as with many EMC tests in general. But, while other tests have gained significant improvements in accuracy and credibility, ESD remains the black sheep of the herd, raising sarcastic jokes among EMC practitioners and lab technicians, who are struggling constantly with these “ESD guns that don’t shoot right” or “ESD tests that make failing products pass and good products fail.” Therefore, a substantial share of the R&D effort has been aimed at reducing the uncertainty attached to ESD generators and test procedures.

However, we have some reservations: While a tremendous amount of activity has been deployed toward ESD generator modeling, calibration, and error analysis that is basically “simulating the simulators,” it seems that the EMC community has lost sight of the actual fact we are trying to counteract: the real, everyday electrostatic discharge. To our knowledge, no organized, wide ranging statistical survey of ESD events has been conducted since the last outstanding work done by R. Simonic around 1973–1974. Things have changed: People’s habits are different: interior decoration, furniture, and clothing are different. Instrumentation that could capture and record ESD is now more accurate, with much greater bandwidth than in the early 1970s. As a result there is a danger that we may very well be trying to reproduce perfectly, with today’s advanced simulators, events as they were recorded 35 years ago.

*St. Remy les Chevreuse, France*  
*May 2009*

MICHEL MARDIGUIAN

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After writing the word *end*, my gratitude goes to those who provided their timely assistance and information: Etienne Sicard and Alain Charoy who gave me valuable details on IC protection, David Pommerenke who shed some light on his very specific series of measurements and modeling, Diethard Mohr and William Rhoades for bringing me up to date on some current ESD documents status. My thanks go also to Joel Raimbourg and Sebastien Bazzoli who provided invaluable support for some practical experiments. Last, but not the least, I am grateful to Mark Montrose and Michael King—the latter being a living memory of the pioneering era of ESD—who expressed their encouragement for the making of this third edition.

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M. M.



# Chapter 1

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## The Electrostatic Discharge Phenomenon

Although a thorough description of the electrostatic phenomenon is beyond the scope of this book and has been covered by several authors (1–4), it might be useful to start by reviewing briefly how static electricity takes place, what are the contributing parameters, and why, eventually, it ends abruptly in its threatening consequence: the electrostatic discharge (ESD).

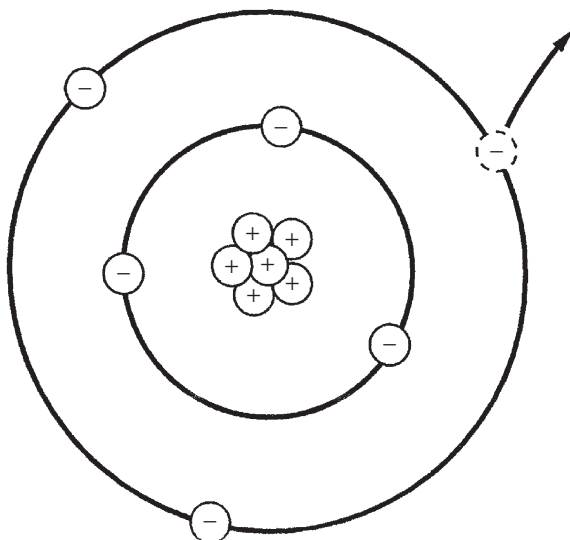
The following section is an extremely simplified view of the electrostatic charging mechanisms. While clearly not a treatise on static electricity, it illustrates the physics involved, in a simple manner. Readers with a good basic knowledge of electrostatics can probably skip this preliminary portion.

### 1.1. PHYSICS INVOLVED

Any material is made of atoms. Unless submitted to certain external influences (heating, rubbing, electrical stress, etc.), the atom is at equilibrium; that is, the amount of negative charges represented by the electrons orbiting around the nucleus is exactly balanced by an equal number of positive charges or protons aggregated in the nucleus. Therefore, the net electric charge seen from the outside is zero.

In good conductors, the mobility of electrons is such that the conditions of equilibrium will always exist; that is, no significant static field will exist between different zones of the same piece of metal. With nonconductive materials, however, the lesser mobility of electrons does not provide such a rapid recombination of charge unbalance. If heated, or rubbed strongly (which also creates heat), a nonconductor will free up electrons.

Depending on the nature of its outer valence orbit, a nonconductive material may be likely to give up electrons or to capture wandering electrons.



**Figure 1.1** If by heating, rubbing, and the like, one electron is leaving the orbit, the material is left with six protons and only five electrons.

A nonconductive material that gives up an electron, as shown in Figure 1.1, will become positively charged. Such unbalanced atoms with a lack of electrons are called *positive ions*. A nonconductive material that takes extra electrons will become negatively charged, and its atoms with excess electrons are called *negative ions*.

Charges with like sign repel while charges with opposite sign attract. Therefore, it seems that nature will rapidly take care of the unbalance by recombining the charges. Unfortunately, while this recombination is instantaneous in metals (i.e., indeed, how a current flows), the high resistance of nonconductive materials makes it unlikely to happen, until such a high gradient of field is reached that either an arc or a mechanical attraction will occur. Besides rubbing or heating, which is the common generation mechanism, an object can become charged by *contact* with another previously charged object.

This ability of nonconductive materials to acquire electrostatic charges is known as triboelectricity. Once a nonconductive material has been subject to triboelectric charging, the charges trapped on its dielectric surface are not easily removed. Grounding the piece of material will do nothing since, on insulators, charges have no mobility. Only a flow of ionized air, hot steam, or conductive liquid can remove the charge unbalance.

Static charging ability is frequently shown on triboelectric scale, such as the one in Table 1.1. Materials labeled “positive” will take on a positive charge every time they are frictioned against a material lower on the scale. Although this kind of scale is true overall, the precise ranking of each material within the scale should not be definitely relied upon in real-life situations. Many authors and practitioners in the ESD community, such as A. Testone (3), have shown how deceptive such triboelectric tables can be.

**Table 1.1** Triboelectric Series

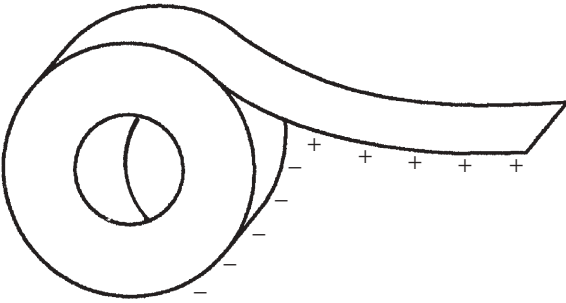
|                 |                                      |
|-----------------|--------------------------------------|
| <b>More (+)</b> | Dry air                              |
|                 | Plexiglass                           |
|                 | Bakelite                             |
|                 | Cellulose acetate                    |
|                 | Silicon wax                          |
|                 | Glass, mica                          |
|                 | Nylon                                |
|                 | Wool                                 |
|                 | Human hair                           |
|                 | Silk                                 |
|                 | Paper, cotton, wood                  |
|                 | Amber, resins (natural or synthetic) |
|                 | Styrofoam, polyurethane              |
|                 | Polyethylene                         |
|                 | Rubber                               |
|                 | Rayon, Dacron, Orlon                 |
|                 | PVC                                  |
|                 | Silicon                              |
|                 |                                      |
|                 |                                      |
| <b>More (−)</b> | Teflon                               |

For example, let us take a reel of ordinary office adhesive tape. If we quickly unwind some length of tape, everyone knows that this segment becomes charged and can attract small particles of dust, hairs etc and the like. But since both sides of the tape are the same material, they rank the same (e.g., positive for acetate) on the table, and this piece of film could not develop an electric field against itself.

However, after unwinding this short segment (Fig. 1.2), we notice that it is strongly attracted by the rest of the reel, which indicates that *there has been a charge transfer*, whereas one side of the tape has acquired electrons that the other side has lost. How can the same material be at the same time a “taker” and a “giver” of electrons, thus contradicting the triboelectric scale? Furthermore, if we cut this piece of tape (using insulating gloves and scissors to prevent our conductive body from influencing the results), and approach it to the reel, some areas of the tape are attracted, while others may be repelled.

The mechanisms coming into play in this apparently simple experiment are multiple and complex. For one, the materials involved are not just acetate against acetate; there is the adhesive layer and also the air itself, which is on the top (+) side of the scale. Then, the tape surfaces have changed their radii as they were separated, such as the “run-away” electrons do not face exactly the same region as when the contact was tight.

Therefore, even two insulating materials of the same nature can eventually develop opposite charges if sufficient friction, shear, or bending is applied. This happens hundreds times a day in a photocopier when foil is slipped over the paper stack.



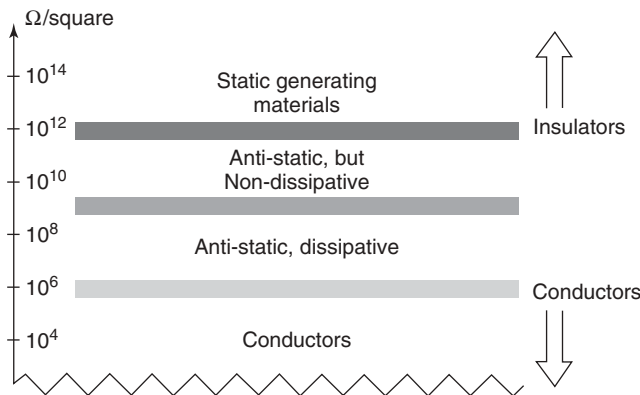
**Figure 1.2** Stripped end of acetate tape is attracted by the surface of the tape reel.

Thus, although triboelectric scale is a fair indication of the polarity of the charge acquired by materials, we must stay away from peremptory statements when facing an electrostatic charging situation. Static field meters are good instruments to get a true measure of the static voltage acquired by various materials.

Now consider the classical example of a person walking on a synthetic carpet, rubbing his body on an insulated chair pad, or moving his nylon shirt sleeve over a polyvinyl chloride (PVC) surface: the farther apart the two materials are on the triboelectric scale and the faster the relative motion of the person, the more electrons will be freed by the givers and captured by the takers. This creates a charge unbalance—hence a latent electric field.

Figure 1.3 suggests a scale of merit for the propensity of materials to create more or less ESD problems. It is based on the surface resistance in ohms per square (i.e., the resistance of a sample square, whether it is 1 cm<sup>2</sup> or 1 m<sup>2</sup>, yields the same results).

Material with more than 10<sup>9</sup> Ω/square are likely to develop electrostatic potentials that will not bleed-off by themselves due to the high insulation of



**Figure 1.3** Propensity of materials to create ESD problems, based on surface resistance in ohms/square.

the material. Materials with less than  $10^9 \Omega/\text{square}$ , even if not real conductors, will not keep the charge unbalance very long because recombination will occur through the material itself.

Aguet (5) relates the propensity to electrostatic charge to the dielectric constant of the materials that are rubbed. He indicates the surface charge density  $\sigma_s$ :

$$\sigma_s = 15 \times 10^{-6}(\epsilon_{r1} - \epsilon_{r2}) \text{ Coulomb/m}^2 \quad (1.1)$$

where  $\epsilon_{r1}$ ,  $\epsilon_{r2}$  are the relative permittivity of the two materials.

For instance, if one looks at a rubber shoe sole ( $\epsilon_{r1} = 2.5$ ) representing  $250 \text{ cm}^2$  and a nylon carpet ( $\epsilon_r = 5$ ), the maximum total charge  $Q$  that can be acquired is

$$\begin{aligned} Q &= 15 \times 10^{-6}(5-2.5)250 \times 10^{-4} \text{ m}^2 \\ &= 0.93 \times 10^{-6} \text{ Coulomb} \end{aligned}$$

If the corresponding foot-to-ground capacitance  $C$  is about 100 pF, the static voltage is derived from

$$Q = CV \quad (1.2)$$

Hence,

$$V = \frac{Q}{C} = 9300 \text{ V}$$

It might seem, therefore, that there is practically no upper limit to what voltage a person can attain. Why not 50 kV 100 kV? Richman, in his very illustrative pamphlet on ESD (6), explains that, hopefully, personnel electrostatic voltage cannot exceed 30 kV in the most extreme cases because:

1. The capacitance of the human body, no matter what we do, cannot drop below 30–40 pF, a value that Richman calls our “capacitance to infinity.”
2. Above approximately 25 kV, the corona will start to self-limit our voltage by bleeding off the charge, that is, the assumption of constant charge  $Q$  is no longer valid.

So, in most practical situations, the upper range of human body static voltage is 20–25 kV.

Summarizing this short description of electrostatic charging, we can say that static electrification is a complex phenomenon that one cannot solely characterize by any single parameter, such as the ranking of the material on a triboelectric scale, its surface resistivity, or dielectric constant. To the contrary, static dissipation can be dependably related to resistivity.

## 1.2. INFLUENCING PARAMETERS

Once the type of materials present is known, the most important parameter is relative humidity. It is well known that, during winter and spring seasons, all integrated circuit manufacturers have recorded an increased rate of “infant mortality” in their chips, and field engineers report an increasing number of service calls for computer failures.

Several things happen when relative humidity is low:

- Normally, the moisture content in the air tends to decrease the surface resistance of floors, carpets, table mats, and the like by letting wet particles create a vaguely conductive (or say, less than  $10^9 \Omega/\text{square}$ ) film over an otherwise insulating surface. If the relative humidity decreases, this favorable phenomenon disappears.
- The air itself, being dry becomes a part of the electrostatic buildup mechanism every time there is an airflow (wind, air conditioning, blower) passing over an insulated surface.

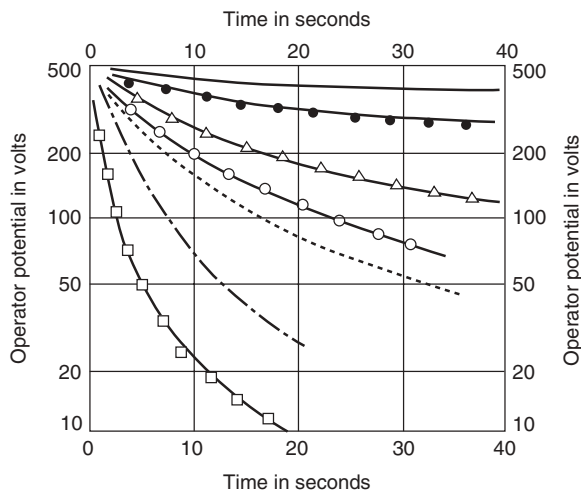
Many evaluations have been made of the electrostatic voltages reached by a person walking on several types of floors. Generally, these tests are made using a kind of “standard walking procedure.” The person walks a given number of steps with a given type of shoes; then his (her) charging voltage is immediately measured with an electrostatic voltmeter having a quasi-infinite input impedance.

The importance of measuring the voltage immediately after charging, and preferably having this same short time for all experiments, is seen in Figure 1.4. If the time elapsed between the end of the charging phase and the instant of the measurement is not kept constant, comparisons between materials, clothes, shoes, and the like become inaccurate.

Figure 1.5 shows the range of acquired electrostatic voltages for several floor types and two values of the relative humidity (RH). On the left side, the voltages are shown for an RH of 50%. Even with a notoriously bad type of carpet such as nylon, the voltage stays within 1–3 kV. Note that this is already enough to kill some integrated circuits if the person touches directly a module or a printed circuit board (PCB). But the scale in the middle merely suggests the likely consequences when the charged person touches a typical electronic cabinet, *without direct contact* to a module or connector pin. What is shown as “likely consequences” assumes that the stressed equipment is of an ordinary design, not especially hardened against ESD. (Chapter 5 will explain how a system can be made reasonably immune to ESD.)

The right side of the chart shows what happens with the same kind of floor coverings when RH goes down to 20%. Nylon jumps to 6–11 kV, and some other synthetic carpets cause people to charge up to 8 kV.

The diagram in Figure 1.5 is restricted to the most current types of floors. With some specific materials, things can go even worse. The worst floor ever is probably a silicon waxed wooden floor where human ESD voltages over 20 kV



Legend

|       | Shoe sole              | Floor                | RH  |
|-------|------------------------|----------------------|-----|
| —     | Composition or leather | Vinyl                | 4%  |
| —●—   | Leather                | Conductive (0.27 MΩ) | 5%  |
| —△—   | Composition            | Conductive (0.95 MΩ) | 4%  |
| —○—   | Leather                | Conductive (0.27 MΩ) | 45% |
| ----- | Composition            | Conductive (0.27 MΩ) | 5%  |
| -.-.- | Composition            | Conductive (0.27 Ω)  | 45% |
| —□—   | Conductive             | Conductive           |     |

**Figure 1.4** Electrostatic-generated voltages will decay at a rate that is dependent on relative humidity, floor covering, and type of clothing worn by personnel. Decay times can take several minutes to reach safe levels (7).

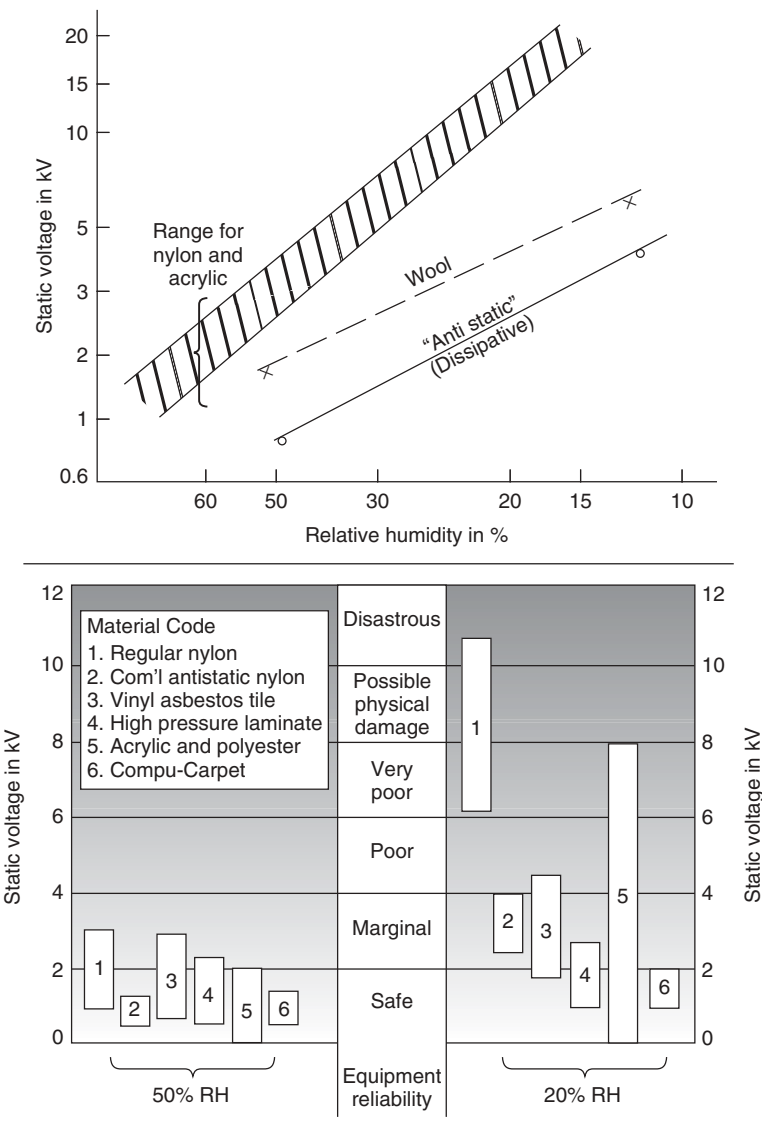
have been commonly reported. A well-known, and often painful, static environment is that of an automobile interior (Fig. 1.6), since a car is a metallic envelope isolated by its tires and replete with plastic and synthetic textiles.

It may seem that a relative humidity of 20% is a rather low. Indeed, as shown in Table 1.2 for relative humidity over the year in major U.S. cities, only a few locations have an RH less than 20%. But in absolute numbers, cities such as Albuquerque, Tucson, and Phoenix are industrial/business areas representing millions of people with hundreds of thousands of electronic devices installed, which must function correctly, even during the winter/spring months.

In fact, the problem is more critical than Table 1.2 would have us believe: The recorded RH values are those found outdoors by the weather bureau. A significant difference may exist between the RH outdoors and its actual value in a heated building. This is due to the fact that, given the same quantity of water, warm air has a greater ability to absorb moisture; therefore, its relative humidity (compared to saturation) is lower.

Equation (1.3) shows that in a restricted space whose temperature is  $T_2$ , the relative humidity is

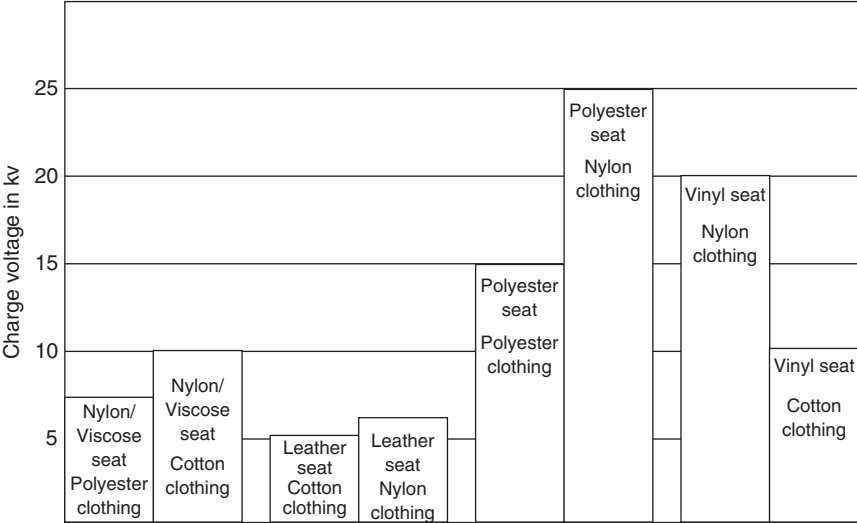
$$RH_{2(T_2)} = RH_{1(T_1)} \frac{T_2}{T_1} e^{C(1/T_2 - 1/T_1)} \tag{1.3}$$



**Figure 1.5** Typical range of static voltages generated by walking on common floor covering materials (adapted from Ref. 8).

where  $RH_1$  is the relative humidity of the outer ambient, at temperature  $T_1$ , and  $C$  a constant equal to 5370 between  $-20^{\circ}\text{C}$  and  $+70^{\circ}\text{C}$ ;  $T_1$  and  $T_2$  in the formula are given in kelvins.

The equation has been plotted in Figure 1.7 for a few typical situations. For instance, on a winter day where the outside temperature is  $0^{\circ}\text{C}$  ( $273^{\circ}\text{K}$ ) and the



**Figure 1.6** Electrostatic charging voltages for various car driver/car seat combinations (9).

RH about 40%, the actual RH in a room heated at 22°C will be only 9%! Unless the heating, ventilation, or air-conditioning system (if there is one) compensates for this lack of water vapor, which it generally does rather poorly, or a humidifier is installed, the ESD risk is very high.

Besides the type of material and the relative humidity, other factors play a role in the severity of the human electrostatic charge:

- Type of clothing and shoes
- Speed and manner of walking
- Sex and size of the person
- Body capacitance
- Body resistance

The two last factors will be discussed in the next section because they strongly influence the dynamic characteristics of the discharge.

**1.3. VARIOUS TYPES OF ELECTROSTATIC CHARGING WITH HUMANS AND OBJECTS**

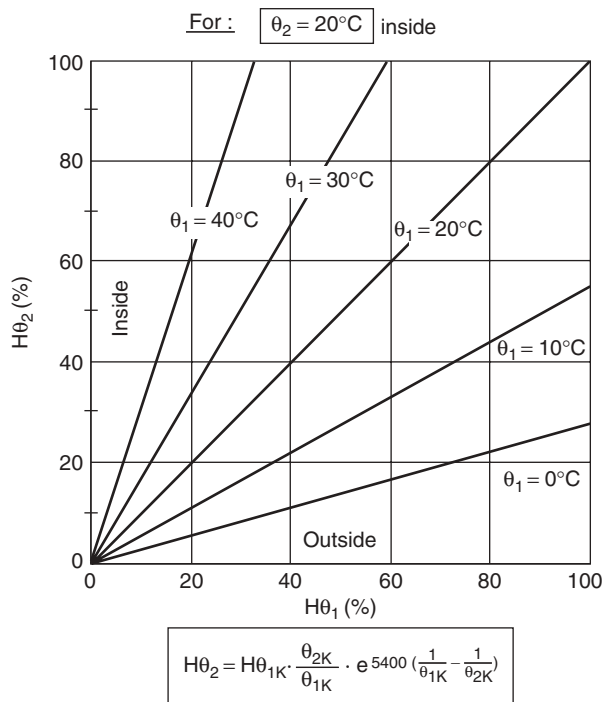
Although an infinity of ESD cases have been reported, the ones that are plaguing the electronic industry belong to either the human body discharge or the charged object discharge. (9) So far, we have emphasized the electrostatic charges generated by human beings, as shown in the most common scenarios of Figure 1.8.

Table 1.2

Relative Humidity  
in Selected U.S. Cities

| STATE   | STATION              | Length<br>of<br>record<br>(yr.) | Jan.         |              | Mar.         |              | May          |              | July         |              | Sept.        |              | Nov.         |              | Annual       |              |
|---------|----------------------|---------------------------------|--------------|--------------|--------------|--------------|--------------|--------------|--------------|--------------|--------------|--------------|--------------|--------------|--------------|--------------|
|         |                      |                                 | 7:00<br>a.m. | 1:00<br>p.m. | 7:00<br>a.m. | 1:00<br>p.m. | 7:00<br>a.m. | 1:00<br>p.m. | 7:00<br>a.m. | 1:00<br>p.m. | 7:00<br>a.m. | 1:00<br>p.m. | 7:00<br>a.m. | 1:00<br>p.m. | 7:00<br>a.m. | 1:00<br>p.m. |
| Ala.    | Mobile               | 17                              | 81           | 62           | 83           | 56           | 86           | 54           | 89           | 61           | 88           | 61           | 85           | 56           | 85           | 57           |
| Alaska  | Juneau               | 36                              | 79           | 76           | 79           | 69           | 74           | 62           | 81           | 70           | 87           | 77           | 85           | 81           | 81           | 73           |
| Ariz.   | Phoenix              | 19                              | 45           | 32           | 33           | 23           | 18           | 13           | 28           | 20           | 31           | 23           | 37           | 28           | 32           | 22           |
| Ark.    | Little Rock          | 19                              | 80           | 62           | 78           | 56           | 86           | 57           | 87           | 58           | 89           | 59           | 82           | 57           | 83           | 57           |
| Calif.  | Los Angeles          | 20                              | 56           | 60           | 62           | 65           | 66           | 66           | 69           | 68           | 66           | 67           | 57           | 63           | 62           | 65           |
|         | Sacramento           | 19                              | 85           | 70           | 68           | 52           | 50           | 36           | 47           | 28           | 50           | 31           | 75           | 59           | 63           | 46           |
|         | San Francisco        | 20                              | 79           | 67           | 70           | 63           | 64           | 60           | 66           | 60           | 65           | 59           | 73           | 64           | 69           | 62           |
| Colo.   | Denver               | 19                              | 45           | 46           | 42           | 40           | 39           | 37           | 35           | 36           | 34           | 45           | 50           | 40           | 40           | 40           |
| Conn.   | Hartford             | 20                              | 72           | 57           | 72           | 53           | 73           | 47           | 79           | 51           | 87           | 56           | 80           | 57           | 77           | 53           |
| Del.    | Wilmington           | 32                              | 75           | 60           | 74           | 53           | 76           | 53           | 80           | 54           | 85           | 56           | 80           | 56           | 78           | 55           |
| D.C.    | Washington           | 19                              | 68           | 54           | 68           | 49           | 72           | 51           | 76           | 53           | 80           | 56           | 74           | 53           | 73           | 52           |
| Fla.    | Jacksonville         | 43                              | 87           | 57           | 85           | 49           | 84           | 50           | 88           | 58           | 91           | 62           | 89           | 55           | 87           | 55           |
|         | Miami                | 15                              | 84           | 60           | 82           | 56           | 82           | 61           | 85           | 64           | 89           | 66           | 85           | 61           | 84           | 62           |
| Ga.     | Atlanta              | 19                              | 78           | 60           | 78           | 51           | 83           | 55           | 90           | 63           | 90           | 61           | 82           | 54           | 83           | 57           |
| Hawaii  | Honolulu             | 10                              | 80           | 63           | 73           | 58           | 67           | 55           | 66           | 51           | 66           | 52           | 74           | 59           | 71           | 56           |
| Idaho   | Boise                | 40                              | 73           | 70           | 55           | 44           | 45           | 34           | 33           | 21           | 39           | 30           | 65           | 60           | 52           | 44           |
| Ill.    | Chicago              | 21                              | 76           | 68           | 79           | 62           | 76           | 54           | 81           | 57           | 84           | 57           | 80           | 64           | 79           | 60           |
|         | Peoria               | 20                              | 77           | 68           | 81           | 54           | 81           | 57           | 85           | 58           | 88           | 58           | 82           | 66           | 87           | 61           |
| Ind.    | Indianapolis         | 20                              | 81           | 70           | 80           | 63           | 82           | 57           | 87           | 60           | 91           | 59           | 85           | 67           | 84           | 62           |
| Iowa    | Des Moines           | 18                              | 76           | 66           | 78           | 63           | 78           | 55           | 81           | 57           | 84           | 59           | 79           | 64           | 80           | 61           |
| Kans.   | Wichita              | 26                              | 79           | 63           | 76           | 54           | 83           | 55           | 78           | 49           | 82           | 55           | 79           | 57           | 79           | 55           |
| Ky.     | Louisville           | 19                              | 77           | 65           | 76           | 59           | 83           | 56           | 86           | 59           | 89           | 60           | 79           | 61           | 81           | 59           |
| La.     | New Orleans          | 31                              | 85           | 67           | 85           | 61           | 89           | 60           | 91           | 66           | 89           | 66           | 86           | 61           | 88           | 63           |
| Maine   | Portland             | 39                              | 77           | 62           | 75           | 59           | 75           | 56           | 80           | 60           | 86           | 61           | 84           | 63           | 80           | 60           |
| Md.     | Baltimore            | 26                              | 71           | 58           | 71           | 51           | 77           | 53           | 82           | 53           | 85           | 56           | 77           | 55           | 77           | 54           |
| Mass.   | Boston               | 15                              | 68           | 58           | 68           | 57           | 71           | 58           | 73           | 56           | 79           | 61           | 75           | 61           | 72           | 58           |
| Mich.   | Detroit              | 45                              | 78           | 69           | 77           | 60           | 71           | 51           | 74           | 51           | 82           | 55           | 79           | 64           | 77           | 58           |
|         | Sault Ste. Marie     | 36                              | 82           | 76           | 83           | 68           | 80           | 56           | 89           | 62           | 87           | 67           | 87           | 76           | 85           | 67           |
| Minn.   | Duluth               | 18                              | 74           | 68           | 77           | 63           | 75           | 54           | 83           | 56           | 86           | 63           | 80           | 69           | 80           | 63           |
|         | Minneapolis-St. Paul | 20                              | 72           | 66           | 76           | 63           | 76           | 52           | 81           | 54           | 86           | 60           | 80           | 66           | 79           | 60           |
| Miss.   | Jackson              | 16                              | 87           | 66           | 88           | 57           | 92           | 56           | 93           | 60           | 94           | 61           | 91           | 58           | 91           | 59           |
| Mo.     | Kansas City          | 7                               | 74           | 65           | 78           | 62           | 83           | 59           | 82           | 56           | 86           | 60           | 78           | 62           | 80           | 60           |
|         | St. Louis            | 19                              | 83           | 66           | 82           | 58           | 83           | 56           | 86           | 57           | 91           | 59           | 85           | 63           | 84           | 60           |
| Mont.   | Great Falls          | 18                              | 53           | 62           | 53           | 48           | 46           | 40           | 38           | 29           | 45           | 36           | 55           | 54           | 50           | 45           |
| Neb.    | Omaha                | 15                              | 78           | 65           | 76           | 57           | 79           | 55           | 83           | 56           | 87           | 61           | 80           | 62           | 80           | 59           |
| Nev.    | Reno                 | 16                              | 68           | 50           | 47           | 33           | 33           | 25           | 28           | 19           | 34           | 21           | 56           | 41           | 44           | 31           |
| N.H.    | Concord              | 14                              | 74           | 60           | 78           | 56           | 79           | 48           | 86           | 52           | 91           | 57           | 85           | 61           | 82           | 55           |
| N.J.    | Atlantic City        | 15                              | 75           | 58           | 76           | 55           | 79           | 57           | 84           | 58           | 86           | 59           | 82           | 57           | 80           | 57           |
| N. Mex. | Albuquerque          | 19                              | 59           | 32           | 34           | 24           | 17           | 35           | 27           | 40           | 31           | 42           | 35           | 37           | 28           | 28           |
| N.Y.    | Albany               | 14                              | 79           | 64           | 74           | 54           | 76           | 52           | 80           | 54           | 88           | 59           | 81           | 63           | 79           | 57           |
|         | Buffalo              | 19                              | 80           | 74           | 80           | 67           | 76           | 56           | 79           | 55           | 83           | 60           | 82           | 70           | 80           | 63           |
|         | New York             | 58                              | 68           | 60           | 67           | 55           | 71           | 53           | 75           | 56           | 79           | 57           | 73           | 59           | 72           | 56           |
| N.C.    | Charlotte            | 19                              | 78           | 56           | 80           | 51           | 84           | 54           | 88           | 59           | 90           | 58           | 84           | 53           | 83           | 54           |
|         | Raleigh              | 15                              | 79           | 65           | 80           | 49           | 87           | 56           | 90           | 59           | 93           | 60           | 85           | 51           | 85           | 54           |
| N. Dak. | Bismarck             | 20                              | 72           | 66           | 78           | 62           | 79           | 49           | 83           | 47           | 82           | 49           | 79           | 62           | 79           | 56           |
| Ohio    | Cincinnati           | 17                              | 79           | 68           | 77           | 60           | 80           | 54           | 85           | 57           | 88           | 59           | 80           | 63           | 81           | 60           |
|         | Cleveland            | 19                              | 77           | 70           | 78           | 65           | 77           | 58           | 82           | 58           | 84           | 61           | 79           | 66           | 79           | 63           |
|         | Columbus             | 20                              | 76           | 68           | 73           | 58           | 79           | 55           | 84           | 56           | 88           | 59           | 81           | 64           | 80           | 59           |
| Okla.   | Oklahoma City        | 14                              | 79           | 61           | 75           | 62           | 83           | 58           | 81           | 50           | 84           | 56           | 78           | 54           | 80           | 54           |
| Oreg.   | Portland             | 39                              | 82           | 76           | 72           | 60           | 66           | 53           | 61           | 45           | 67           | 49           | 82           | 74           | 72           | 60           |
| Pa.     | Philadelphia         | 20                              | 73           | 59           | 71           | 53           | 75           | 53           | 79           | 55           | 83           | 57           | 77           | 56           | 76           | 55           |
|         | Pittsburgh           | 19                              | 76           | 66           | 74           | 58           | 76           | 51           | 82           | 53           | 86           | 57           | 79           | 63           | 78           | 57           |
| R.I.    | Providence           | 16                              | 72           | 58           | 70           | 54           | 72           | 52           | 77           | 57           | 82           | 57           | 78           | 59           | 75           | 55           |
| S.C.    | Columbia             | 13                              | 82           | 55           | 83           | 48           | 87           | 51           | 89           | 56           | 93           | 58           | 86           | 49           | 87           | 52           |
| S. Dak. | Sioux Falls          | 16                              | 74           | 67           | 80           | 63           | 80           | 53           | 81           | 52           | 85           | 57           | 82           | 64           | 80           | 59           |
| Tenn.   | Memphis              | 40                              | 78           | 63           | 76           | 56           | 82           | 55           | 85           | 57           | 86           | 56           | 79           | 55           | 81           | 57           |
|         | Nashville            | 14                              | 80           | 65           | 78           | 54           | 87           | 56           | 91           | 59           | 92           | 61           | 81           | 59           | 85           | 58           |
| Tex.    | Dallas-Fort Worth    | 18                              | 80           | 61           | 80           | 57           | 88           | 61           | 81           | 50           | 87           | 59           | 81           | 56           | 82           | 57           |
|         | El Paso              | 19                              | 44           | 34           | 28           | 20           | 22           | 15           | 39           | 29           | 44           | 34           | 38           | 32           | 35           | 27           |
|         | Houston              | 10                              | 66           | 66           | 69           | 60           | 84           | 60           | 94           | 59           | 85           | 65           | 91           | 60           | 82           | 60           |
| Utah    | Salt Lake City       | 20                              | 70           | 68           | 52           | 45           | 37           | 31           | 26           | 20           | 34           | 27           | 57           | 58           | 46           | 42           |
| Vi.     | Burlington           | 14                              | 70           | 64           | 73           | 59           | 75           | 51           | 80           | 54           | 87           | 64           | 79           | 69           | 78           | 60           |
| Va.     | Norfolk              | 31                              | 75           | 59           | 74           | 54           | 78           | 57           | 82           | 60           | 84           | 62           | 79           | 56           | 78           | 58           |
|         | Richmond             | 45                              | 81           | 57           | 78           | 49           | 79           | 51           | 85           | 57           | 90           | 57           | 85           | 50           | 83           | 53           |
| Wash.   | Seattle-Tacoma       | 20                              | 74           | 74           | 62           | 67           | 54           | 65           | 74           | 59           | 80           | 74           | 73           | 68           | 74           | 62           |
|         | Spokane              | 20                              | 82           | 77           | 67           | 54           | 52           | 40           | 39           | 25           | 50           | 34           | 81           | 74           | 62           | 51           |
| W. Va.  | Charleston           | 32                              | 77           | 63           | 74           | 53           | 82           | 50           | 90           | 61           | 91           | 56           | 80           | 56           | 82           | 56           |
| Wis.    | Milwaukee            | 19                              | 75           | 68           | 79           | 66           | 79           | 61           | 82           | 61           | 87           | 63           | 81           | 67           | 81           | 65           |
| Wyo.    | Cheyenne             | 20                              | 45           | 48           | 44           | 45           | 39           | 41           | 34           | 37           | 35           | 36           | 42           | 47           | 40           | 42           |
| P.R.    | San Juan             | 24                              | 80           | 64           | 77           | 60           | 77           | 65           | 78           | 66           | 79           | 67           | 81           | 66           | 79           | 64           |

Please note: These figures, given in percentages, represent the averages for the period of record through 1979. Eastern Standard Times are indicated.



$H_\theta$  : Relative humidity at temperature  $\theta$

$\theta$  : Temperature in K (formula valid for  $-20$  to  $+60^\circ\text{C}$ )

**Figure 1.7** Actual vs. apparent relative humidity.

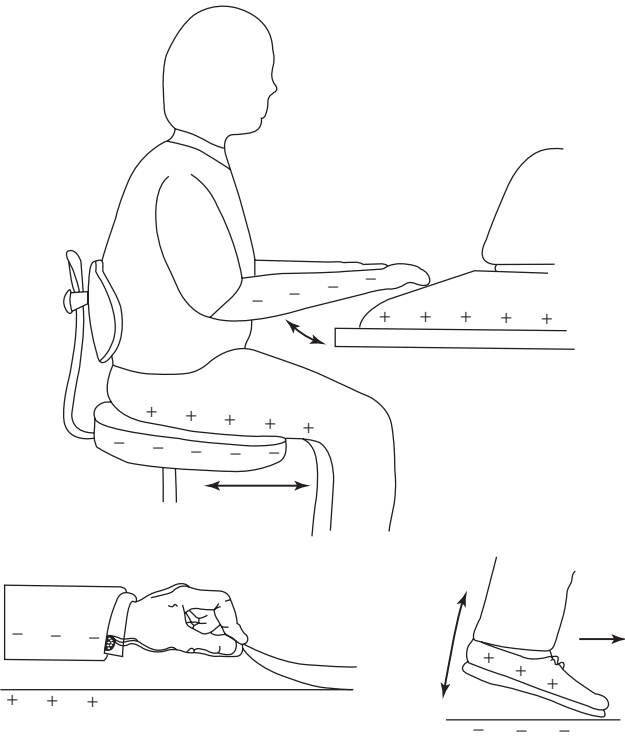
Notice that depending on the nature of the two materials being rubbed together, the person can exhibit positive or negative charging.

Although humans tend to treat themselves as very special, physics does not care and treats us as a mere conglomerate of materials, vaguely conductive. There are thousands of occasions where the human body is not the electrostatic generator, but simply the carrier, or even is not involved at all (Fig. 1.9).

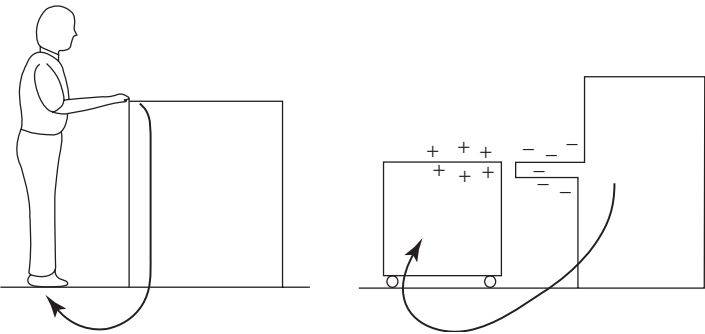
An example of a human as a carrier occurs when a person gets out from a car after a ride on a bright, cold, and windy winter day. The moment he puts his foot on the ground while his hand is touching the door handle, he often feels a violent ESD zap. The body was not the electrostatic generator in this case, the car was. There have been reports of highway toll gate attendants who could not stand their job because of too many ESD zaps when drivers were handling them the money!

Following is a list of some nonhuman ESD sources:

- Wheelchairs, carts, rolling furniture
- Rubber or textile belts and conveyors and their pulleys/rollers
- Cooling fans with plastic rotor blades
- Helicopter rotor blades (generally made of composite material)



**Figure 1.8** Some of the classical ways a human can accumulate static charges.



**Figure 1.9** ESD with or without a human body involved.

- Paper movement (printers, copiers)
- Rapid flow or friction of gas, liquid, or granule against an insulating material or unground conductor such as:
  - Cleaning with airgun
  - PVC “skin-packing” with hot air blast
  - Cleaning with solvent
  - Fuel lines (including filling-in or draining-off a fuel tank)
  - Loading or dumping grains in silos
  - Rocket exhaust nozzle
  - Radomes, fiberglass hoods, and tips
  - Thermal blankets (spacecrafts)
- Device-manipulating robots on manufacturing lines
- Electrostatic painting process (the spray nozzle being charged around 80–100 kV)

Also, we must remember that a nonconductive object can become charged by contact with another, previously charged, object. This static-contaminated object will, in turn, be a potential hazard for electronics.

In all cases, whether a person is involved or not, the charged object will “seek” the first opportunity to recombine the unbalanced charges: This may occur smoothly by a progressive bleed of charges through a moderately conductive path, or may occur abruptly and generally accompanied by an arc.

In the case of a “self”-recombination, a small amount of current will flow during a certain time, and the result will be generally harmless. To the contrary, with an abrupt recombination, the discharge will occur during a very short time due to the high-voltage gradients involved, and the corresponding current will be high. Since its average value is

$$I(A) = \frac{Q(\text{Coulomb})}{t(s)} \quad (1.4)$$

when a discharge of microcoulombs takes place within tens of nanoseconds, the average current amounts to several amperes, with peak values that can reach up to hundreds of amperes.

## 1.4. STATISTICS OF VOLTAGES AND CURRENTS REACHED DURING ESD

Although the ESD phenomenon has been experienced and fought against for decades by electrical and electronics industries, it is only around the early 1970s that thorough studies were carried on its dynamic parameters. Measurements have been published of voltages and/or currents encountered during real or re-created ESD situations, sampled over a certain period of time or among a certain number of individuals. The statistics that have been gathered, to the knowledge of this author, can be classified as follows:

- Measured voltages of human ESD, depending on the materials involved (garments, type of shoes, type of floor covering)
- Measured voltages of human ESD, depending of the relative humidity (correlated or not with the time of the year)
- Measured voltage of objects and furniture ESD, against the type of objects and sometimes the type of environment (humidity and floor covering)
- Measured currents with furniture ESD, against type of environment and time of the year

Although they are more spectacular and seem to relate the most obviously with the severity of the discharge, the data collected on ESD voltages are not the most meaningful, neither are they the most crucial when trying to develop representative specifications for ESD simulation.

The voltages at which the persons were charged during the measurement campaign can be an ambiguous or inaccurate database. Was the voltage measured at its peak, right after a static buildup? Or was it recorded at the moment of an actual discharge? What were the mean value and standard deviation of the voltage decay between its peak value (as generated) and its value at the exact moment of the discharge? Were the people in the study aware that ESD voltages were gathered?

Every statistician knows that people in such surveys often tend to “sympathize” with the experimenter, *helping him to find what he likes to find* (in our case, for instance, by shuffling their shoes more conscientiously on the carpet). Statistics is a discipline requiring specific precautions. In some of the often mentioned experiments, it is not clear that these precautions were taken or were feasible.

Doing a parallel between ESD and lightning, one could say that focusing on ESD voltages only is probably as irrelevant as would be concentrating on cloud-to-Earth voltages when studying lightning strikes: all sound statistics on lightning severity are based on lightning currents. Similarly, ESD statistics based on current seem the most dependable and usable. As for any transient, random events, statistical analysis is important for determining what is the risk that a certain value of electrostatic discharge will be reached (or the probability  $P$  that this value will be exceeded). Do we want to test the immunity of an electronic device or equipment to something that can happen once a day or once a year? How many failures per week or month do we risk by testing a machine only to a certain ESD level?

A rough example of recording the number of electrostatic discharges is shown in Figure 1.10. During a particularly cold and dry spring (early April 1982) in Virginia, the author had taken a limited survey of the number of discharges (as they were felt by people) in a set of offices where about 12 people were using one copier, a telex, a desk-top computer, a postage meter, and a word processor.

Discharges were recorded on Tuesdays, Wednesdays, and Thursdays for 3 weeks. These discharges did not necessarily cause equipment malfunction—in fact most of them did not—but the purpose of the survey was to count the